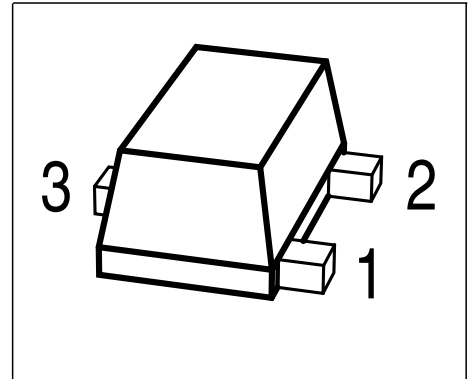


NPN Silicon RF Transistor

Preliminary data

- Low voltage/ low current operation
- For low noise amplifiers
- For Oscillators up to 3.5 GHz and Pout > 10 dBm
- Low noise figure: 1.0 dB at 1.8 GHz



ESD: Electrostatic discharge sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR360F	FBs	1 = B	2 = E	3 = C	TSFP-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	6	V
Collector-emitter voltage	V_{CES}	15	
Collector-base voltage	V_{CBO}	15	
Emitter-base voltage	V_{EBO}	2	
Collector current	I_C	35	mA
Base current	I_B	4	
Total power dissipation ¹⁾ $T_S \leq 98^\circ\text{C}$	P_{tot}	210	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R_{thJS}	≤ 250	K/W

¹⁾ T_S is measured on the collector lead at the soldering point to the pcb

²⁾ For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Collector-emitter breakdown voltage $I_C = 1\text{ mA}$, $I_B = 0$	$V_{(BR)CEO}$	6	9	-	V
Collector-emitter cutoff current $V_{CE} = 15\text{ V}$, $V_{BE} = 0$	I_{CES}	-	-	10	μA
Collector-base cutoff current $V_{CB} = 5\text{ V}$, $I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 1\text{ V}$, $I_C = 0$	I_{EBO}	-	-	1	μA
DC current gain- $I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$	h_{FE}	60	130	200	-

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency $I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$, $f = 1\text{ GHz}$	f_T	11	14	-	GHz
Collector-base capacitance $V_{CB} = 5\text{ V}$, $f = 1\text{ MHz}$, emitter grounded	C_{cb}	-	0.32	0.5	pF
Collector emitter capacitance $V_{CE} = 5\text{ V}$, $f = 1\text{ MHz}$, base grounded	C_{ce}	-	0.2	-	
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$, $f = 1\text{ MHz}$, collector grounded	C_{eb}	-	0.4	-	
Noise figure $I_C = 3\text{ mA}$, $V_{CE} = 3\text{ V}$, $Z_S = Z_{Sopt}$, $f = 1.8\text{ GHz}$	F_{min}	-	1	-	dB
Power gain, maximum available ¹⁾ $I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, $f = 1.8\text{ GHz}$	G_{ma}	-	15.5	-	
$I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, $f = 3\text{ GHz}$		-	11	-	
Transducer gain $I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$, $Z_S = Z_L = 50\Omega$, $f = 1.8\text{ GHz}$ $I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$, $Z_S = Z_L = 50\Omega$, $f = 3\text{ GHz}$	$ S_{21e} ^2$	-	13 9	-	dB
Third order intercept point at output ²⁾ $V_{CE} = 3\text{ V}$, $I_C = 15\text{ mA}$, $f = 1.8\text{ GHz}$, $Z_S = Z_L = 50\Omega$	IP_3	-	24	-	
1dB Compression point at output $I_C = 15\text{ mA}$, $V_{CE} = 3\text{ V}$, $Z_S = Z_L = 50\Omega$, $f = 1.8\text{ GHz}$	P_{-1dB}	-	9	-	

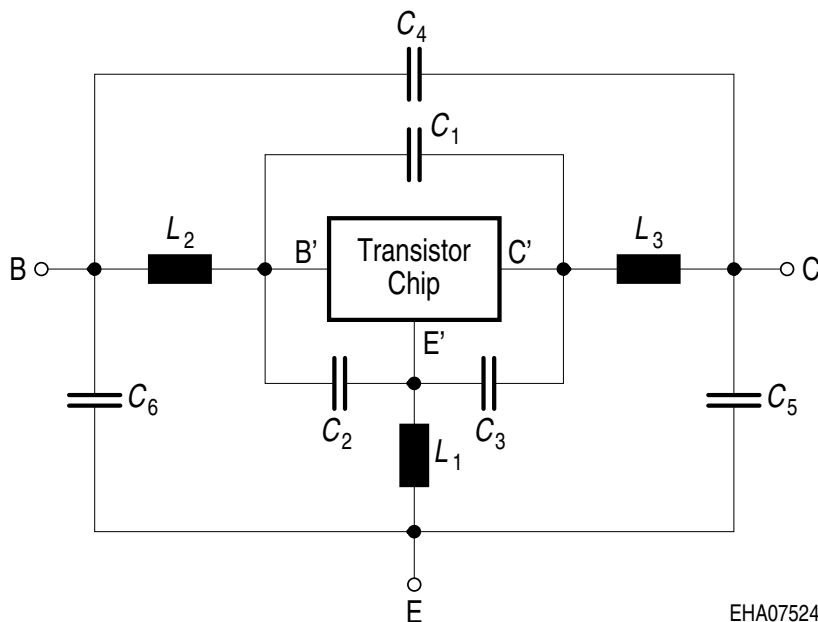
$$^1G_{ma} = |S_{21e}| / |S_{12e}| (k - (k^2 - 1)^{1/2})$$

²⁾IP3 value depends on termination of all intermodulation frequency components.
Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):
Transistor Chip Data:

IS =	0.0689	fA	BF =	147	-	NF =	1	-
VAF =	20	V	IKF =	77.28	mA	ISE =	150	fA
NE =	2.4	-	BR =	6	-	NR =	1	-
VAR =	60	V	IKR =	0.3	A	ISC =	20	fA
NC =	1.4	-	RB =	0.1	Ω	IRB =	75	μ A
RBM =	7.31	Ω	RE =	78.2	m Ω	RC =	0.35	Ω
CJE =	400	fF	VJE =	1.3	V	MJE =	0.5	-
TF =	9.219	ps	XTF =	0.115	-	VTF =	0.198	V
ITF =	1.336	mA	PTF =	0	deg	CJC =	473	fF
VJC =	0.864	V	MJC =	0.486	-	XCJC =	0.129	-
TR =	1.92	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0.5	K	EG =	1.11	eV
XTI =	0	-	FC =	0.954		NK =	0.5	K
AF =	1	-	KF =	1E-14	-			

All parameters are ready to use, no scaling is necessary.

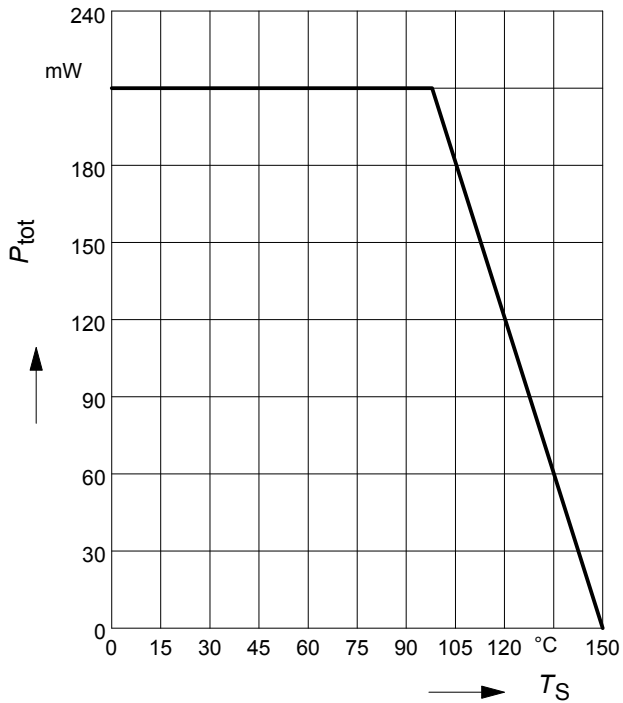
Package Equivalent Circuit:


L_1 =	0.556	nH
L_2 =	0.657	nH
L_3 =	0.381	nH
C_1 =	43	fF
C_2 =	123	fF
C_3 =	66	fF
C_4 =	10	fF
C_5 =	36	fF
C_6 =	47	fF

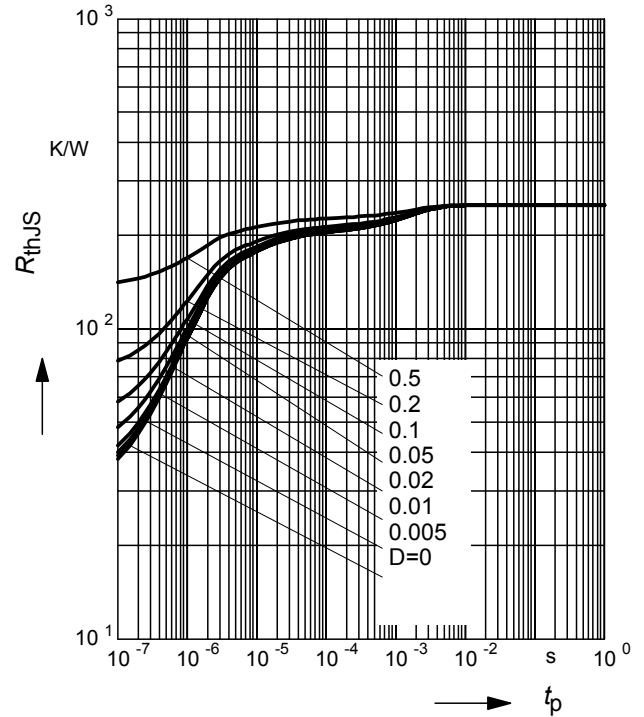
Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: <http://www.infineon.com/silicondiscretes>

Total power dissipation $P_{\text{tot}} = f(T_S)$

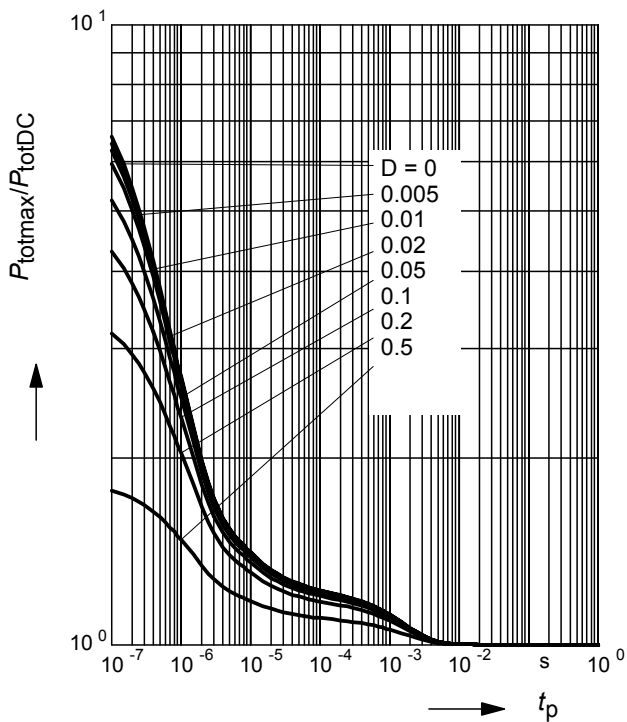


Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$



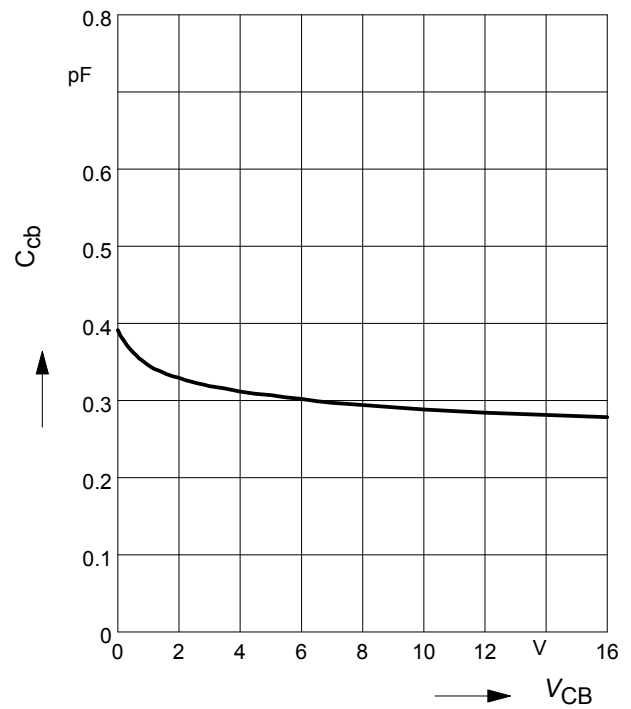
Permissible Pulse Load

$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$



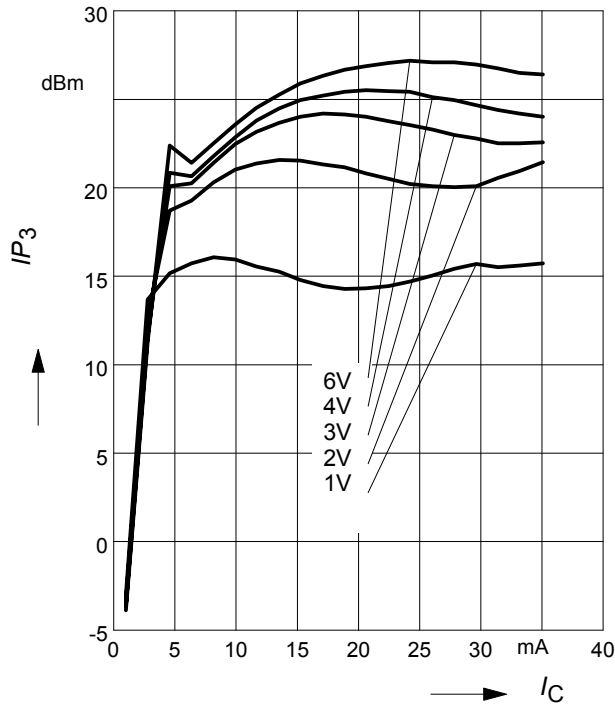
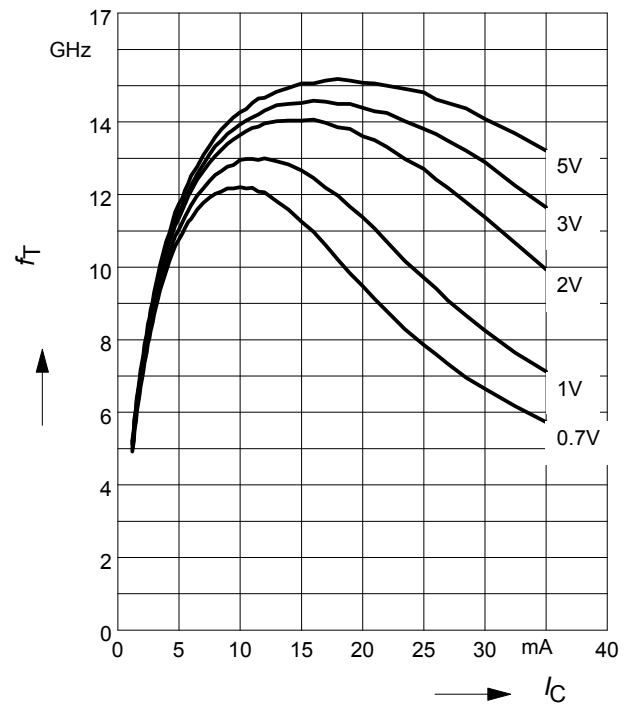
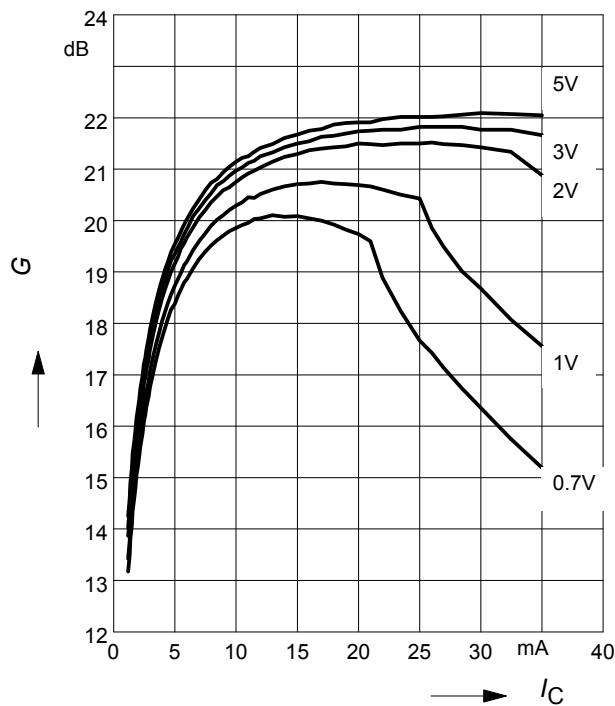
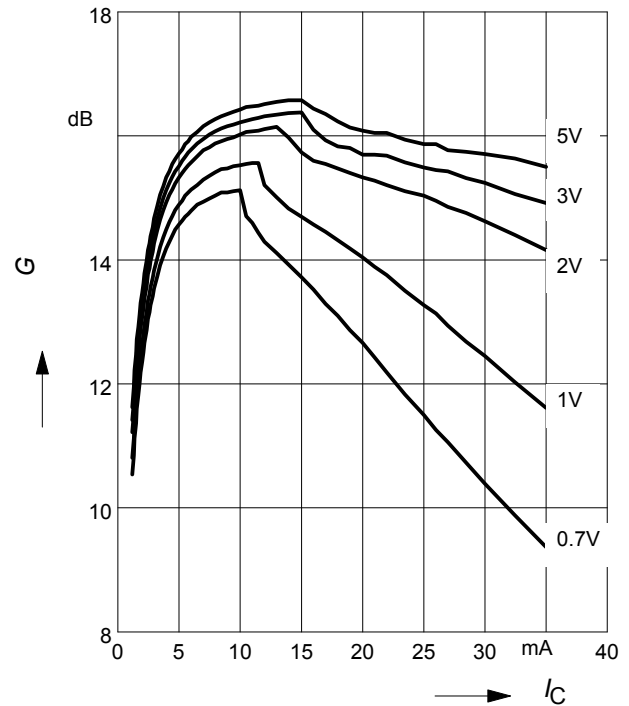
Collector-base capacitance $C_{\text{cb}} = f(V_{\text{CB}})$

$f = 1\text{MHz}$



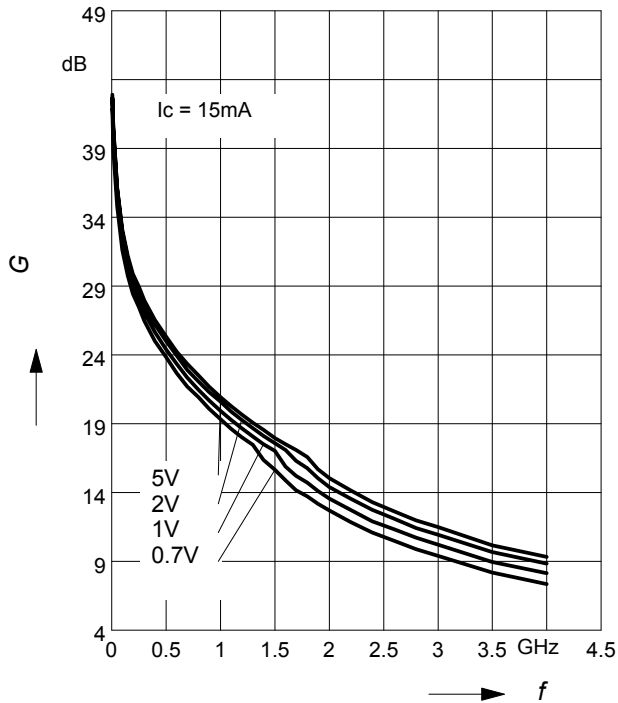
Third order Intercept Point $IP_3 = f(I_C)$

 (Output, $Z_S = Z_L = 50\Omega$)

 V_{CE} = parameter, $f = 1.8\text{GHz}$

Transition frequency $f_T = f(I_C)$
 $f = 1\text{GHz}$
 V_{CE} = parameter

Power gain $G_{ma}, G_{ms} = f(I_C)$
 $f = 0.9\text{GHz}$
 V_{CE} = parameter

Power gain $G_{ma}, G_{ms} = f(I_C)$
 $f = 1.8\text{GHz}$
 V_{CE} = parameter


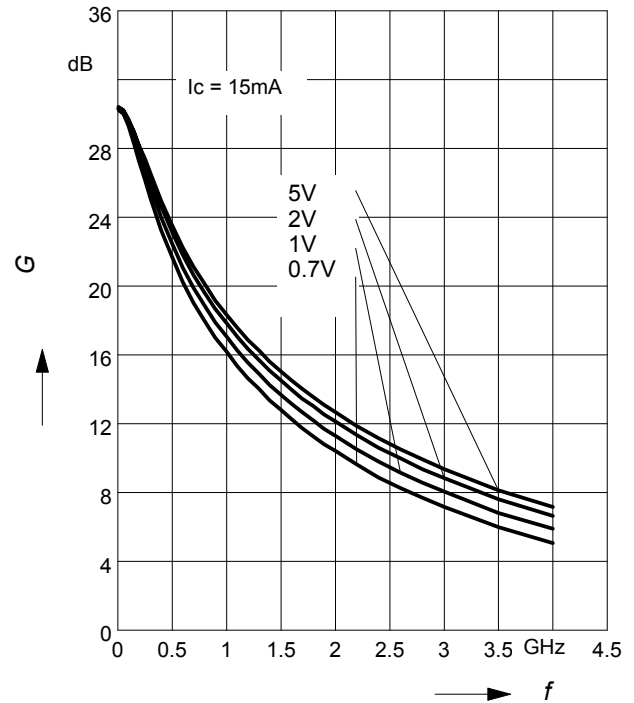
Power Gain G_{ma} , $G_{ms} = f(f)$

$V_{CE} = \text{parameter}$



Insertion Power Gain $|S_{21}|^2 = f(f)$

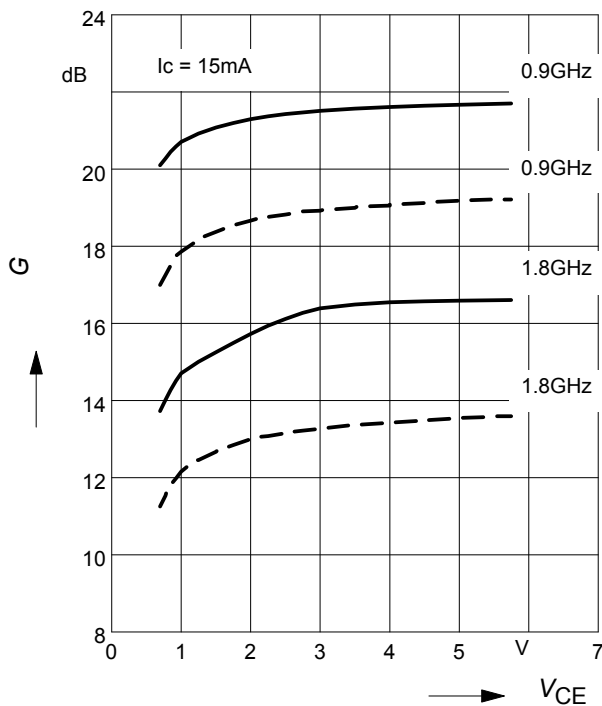
$V_{CE} = \text{parameter}$



Power Gain G_{ma} , $G_{ms} = f(V_{CE})$: —

$|S_{21}|^2 = f(V_{CE})$: - - - -

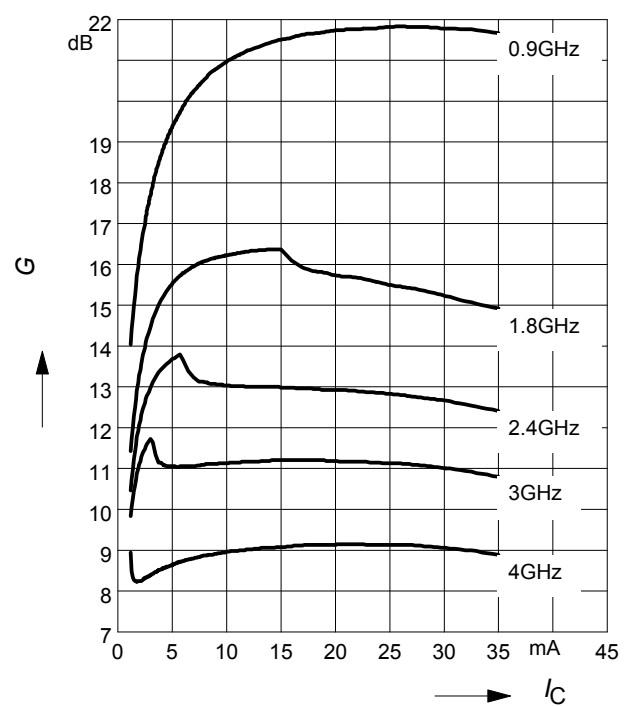
$f = \text{parameter}$



Power gain G_{ma} , $G_{ms} = f(I_C)$

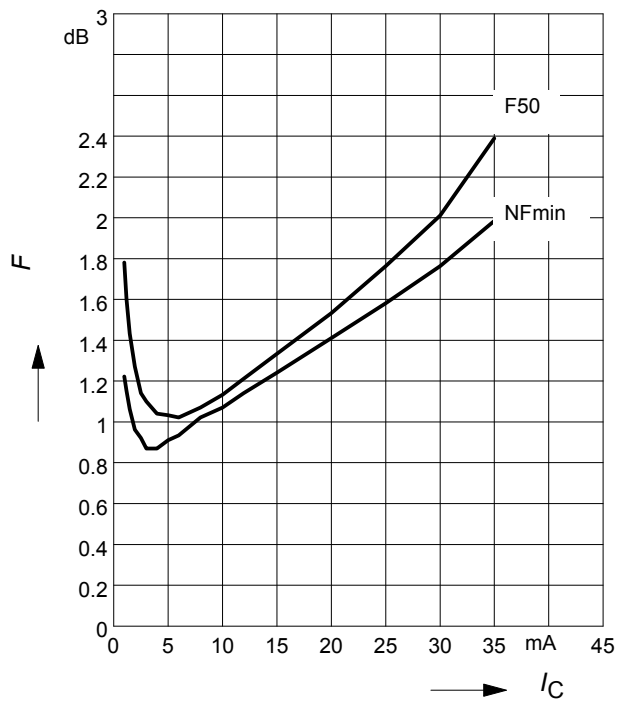
$V_{CE} = 3V$

$f = \text{parameter}$



Noise figure $NF = f(I_C)$

$V_{CE} = 3V$, $f = 1,8 \text{ GHz}$



Source impedance for min.

noise figure vs. frequency

$V_{CE} = 3 \text{ V}$

